

RD Number: RD108

RD Title: TB67B000FG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	R1	0	68kΩ 0.25W ±1%	–	–	Resistor		✓
2		0	Socket pin	–	–	Socket pin		✓
3		1	68kΩ	–	–	Chip resistor 2012		
4	R1A	0	Not mount	–	–	Socket pin		✓
5		0	Not mount	–	–	Chip resistor 2012		✓
6	R2	1	0Ω (Short)	–	–	Short		
7		2	Socket pin	–	–	Socket pin		
8		0	Not mount	–	–	Chip resistor 2012		✓
9	R3	1	0.51Ω 2W ±5%	–	–	Resistor		
10		0	Not mount	–	–	Chip resistor 2512		✓
11	R3A	0	Not mount	–	–			✓
12		0	Not mount	–	–	Chip resistor 2512		✓
13	R4	0	Not mount	–	–			✓
14		0	Not mount	–	–	Chip resistor 2012		✓
15	R5	0	Not mount	–	–			✓
16		0	Not mount	–	–	Chip resistor 2012		✓
17	R6	0	Not mount	–	–			✓
18		0	Not mount	–	–	Chip resistor 2012		✓
19	R7	0	Not mount	–	–			✓
20		0	Not mount	–	–	Chip resistor 2012		✓
21	R8	0	Not mount	–	–			✓
22		0	Not mount	–	–	Chip resistor 2012		✓
23	R9	0	Not mount	–	–			✓
24		0	Not mount	–	–	Chip resistor 2012		✓
25	R10	0	Not mount	–	–			✓
26		0	Not mount	–	–	Chip resistor 2012		✓

27	R11	0	Not mount	-	-			✓
28		0	Not mount	-	-	Chip resistor 2012		✓
29	R12	0	Not mount	-	-			✓
30		0	Not mount	-	-	Chip resistor 2012		✓
31	R13	0	Not mount	-	-			✓
32		0	Not mount	-	-	Chip resistor 2012		✓
33	C1	0	0.01 μ F 50V \pm 10%	-	-	Capacitor		✓
34		0	Socket pin	-	-	Socket pin		✓
35		1	0.01 μ F	-	-	Chip capacitor 1608		
36	C2	1	0.1 μ F 50V \pm 10%	-	-	Capacitor		
37		0	Not mount	-	-	Chip capacitor 1608		✓
38	C3	1	1 μ F 50V \pm 20%	-	-	Electrolytic capacitor		
39		0	Not mount	-	-	SMT		✓
40	C4	1	1000pF 50V \pm 5%	-	-	Capacitor		
41		0	Not mount	-	-	Chip capacitor 1608		✓
42	C5	2	Socket pin	-	-	Socket pin (Open)		
43		0	Not mount	-	-	Chip capacitor		✓
44	C6	1	10 μ F 50V \pm 20%	-	-	Electrolytic capacitor		
45		0	Not mount	-	-	SMT		✓
46	C7	1	0.1 μ F 50V \pm 10%	-	-	Capacitor		
47		0	Not mount	-	-	Chip capacitor 1608		✓
48	C8	1	2.2 μ F 50V \pm 20%	-	-	Electrolytic capacitor		
49		0	Not mount	-	-	Chip capacitor 2012		✓
50	C9	1	2.2 μ F 50V \pm 20%	-	-	Electrolytic capacitor		
51		0	Not mount	-	-	Chip capacitor 2012		✓
52	C10	1	2.2 μ F 50V \pm 20%	-	-	Electrolytic capacitor		
53		0	Not mount	-	-	Chip capacitor 2012		✓
54	C11	1	0.1 μ F 50V \pm 10%	-	-	Capacitor		
55		2	Socket pin	-	-	Socket pin		
56		0	Not mount	-	-	Chip capacitor 1608		✓
57	C12	1	0.1 μ F 50V \pm 10%	-	-	Capacitor		
58		2	Socket pin	-	-	Socket pin		
59		0	Not mount	-	-	Chip capacitor 1608		✓
60	C13	1	0.1 μ F 50V \pm 10%	-	-	Capacitor		

61		2	Socket pin	-	-	Socket pin		
62		0	Not mount	-	-	Chip capacitor 1608		✓
63	C14	0	Not mount	-	-	Capacitor		✓
64		0	Not mount	-	-	Chip capacitor 1608		✓
65	C15	0	Not mount	-	-	Capacitor		✓
66		0	Not mount	-	-	Chip capacitor 1608		✓
67	C16	0	Not mount	-	-	Capacitor		✓
68		0	Not mount	-	-	Chip capacitor 1608		✓
69	C17	0	Not mount	-	-	Capacitor		✓
70		0	Not mount	-	-	SMT		✓
71	C18	0	0.1μF 50V ±10%	-	-	Capacitor		✓
72		1	0.1μF	-	-	Chip capacitor 1608		
73	C19	0	Not mount	-	-	Capacitor		✓
74		0	Not mount	-	-	SMT		✓
75	C20	0	Not mount	-	-	Capacitor		✓
76		0	Not mount	-	-	Chip capacitor 1608		✓
77	C21	0	Not mount	-	-	Capacitor		✓
78		0	Not mount	-	-	Chip capacitor 1608		✓
79	C22	0	Not mount	-	-	Capacitor		✓
80		0	Not mount	-	-	Chip capacitor 1608		✓
81	JP1	0	-	-	-	Short pad		✓
82	JP2	0	-	-	-	Short pad		✓
83	JP3	0	-	-	-	Short pad		✓
84	JP4	0	-	-	-	Short pad		✓
85	JP5-1	1	Short	-	-	Short pad		
86	JP5-2	1	Short	-	-	Short pad		
87	JP6-1	1	Short	-	-	Short pad		
88	JP6-2	1	Short	-	-	Short pad		
89	JP7-1	1	Short	-	-	Short pad		
90	JP7-2	1	Short	-	-	Short pad		
91	JP8	0	-	-	-	Short pad		✓
92	JP9	0	-	-	-	Short pad		✓
93	JP10	0	-	-	-	Short pad		✓
94	JP11	0	-	-	-	Short pad		✓

95	JP12	0	-	-	-	Short pad		✓
96	JP13	0	-	-	-	Short pad		✓
97	JP14	0	-	-	-	Short pad		✓
98	JP15	0	-	-	-	Short pad		✓
99	JP16	0	-	-	-	Short pad		✓
100	JP17-1	1	Short	-	-	Short pad		
101	JP17-2	1	Short	-	-	Short pad		
102	JP17-3	1	Short	-	-	Short pad		
103	JP17-4	1	Short	-	-	Short pad		
104	JP17-5	1	Short	-	-	Short pad		
105	JP17-6	1	Short	-	-	Short pad		
106	JP19-1	1	Short	-	-	Short pad		
107	JP19-2	1	Short	-	-	Short pad		
108	JP19-3	1	Short	-	-	Short pad		
109	JP19-4	1	Short	-	-	Short pad		
110	JP19-5	1	Short	-	-	Short pad		
111	JP19-6	1	Short	-	-	Short pad		
112	JP-1	1	Short	-	-	Short pad		
113	JP-2	1	Short	-	-	Short pad		
114	JP-3	1	Short	-	-	Short pad		
115	JP-4	1	Short	-	-	Short pad		
116	JP-5	1	Short	-	-	Short pad		
117	JP-6	1	Short	-	-	Short pad		
118	FG	1	Check terminal	-	-	Logic pin		
119	VSP	1	Check terminal	-	-	Logic pin		
120	LA	1	Check terminal	-	-	Logic pin		
121	SGND2	1	Check terminal	-	-	Logic pin		
122	HU	0	Check terminal	-	-	Logic pin		✓
123	HV	0	Check terminal	-	-	Logic pin		✓
124	HW	0	Check terminal	-	-	Logic pin		✓
125	Vrefout2	0	Check terminal	-	-	Logic pin		✓
126	SGND3	1	Check terminal	-	-	Logic pin		
127	HUP	1	Check terminal	-	-	Logic pin		
128	HUM	1	Check terminal	-	-	Logic pin		

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